

HOSTAFORM® EC270TX

Rheological properties

Melt volume-flow rate	1.5 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.9 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.7 %	ISO 294-4, 2577

Typical mechanical properties

Tensile Modulus	1950 MPa	ISO 527-1/-2
Yield stress, 50mm/min	44 MPa	ISO 527-1/-2
Yield strain, 50mm/min	11 %	ISO 527-1/-2
Nominal strain at break	15 %	ISO 527-1/-2
Shear Modulus	770 MPa	ISO 6721
Charpy notched impact strength, 23°C	6.5 kJ/m ²	ISO 179/1eA

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	70 °C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	135 °C	ISO 306

Electrical properties

Volume resistivity	10 Ohm.m	IEC 62631-3-1
Surface resistivity	1000 Ohm	IEC 62631-3-2

Other properties

Density	1380 kg/m ³	ISO 1183
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Injection

Drying Temperature	100 - 120 °C	
Drying Time, Dehumidified Dryer	3 - 4 h	
Melt Temperature Optimum	200 °C	Internal

Additional information

Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the Hostaform® material.	
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Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature

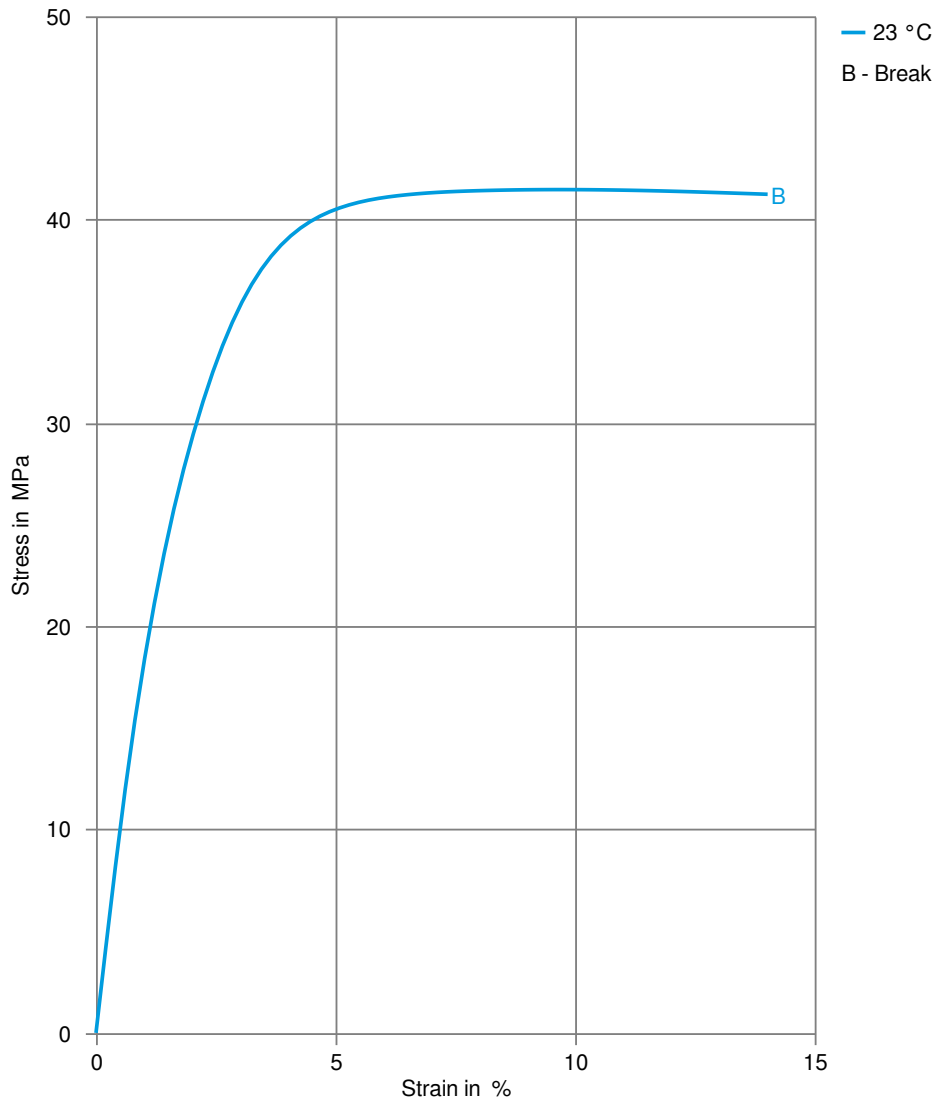
HOSTAFORM® EC270TX

should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may produce a hazy surface or a surface with flow lines, pits and other included defects.

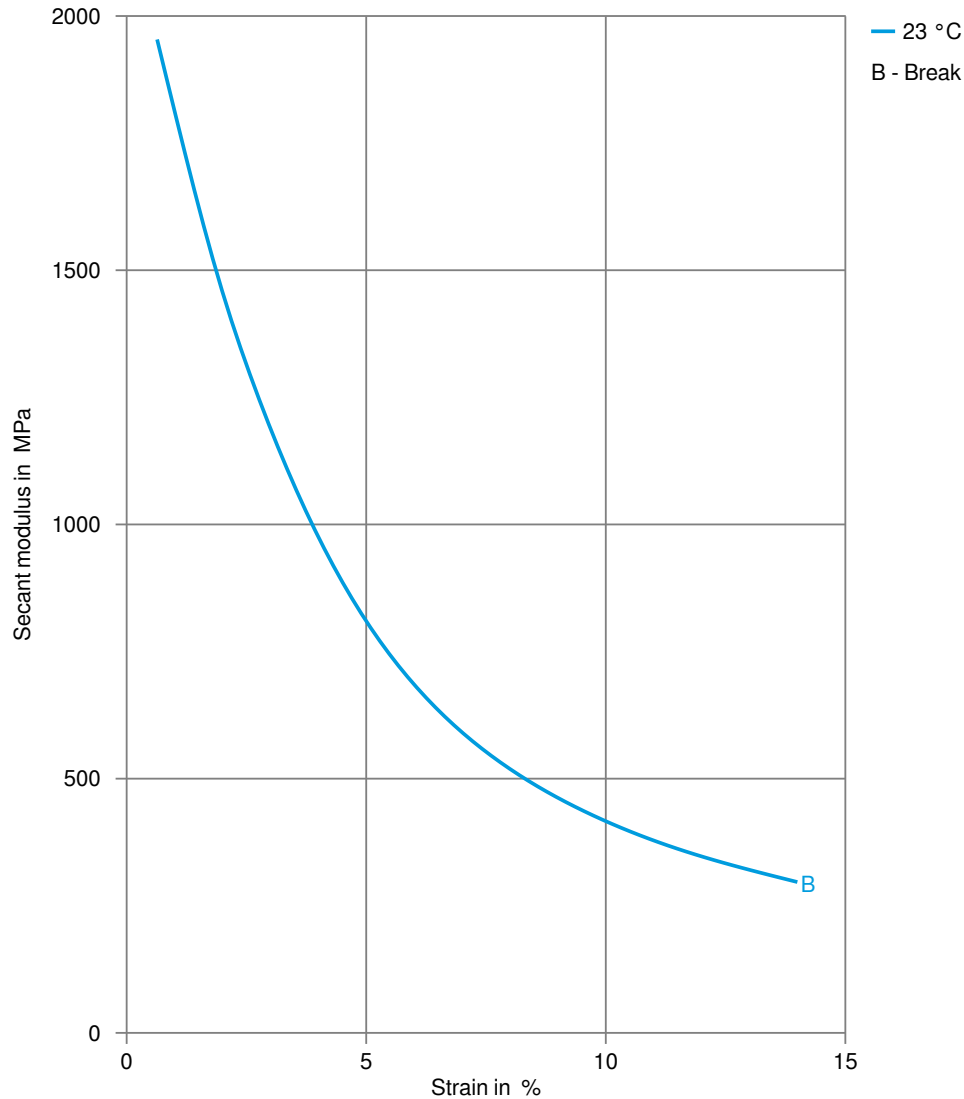
Stress-strain

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Secant modulus-strain



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Processing Texts

Injection molding

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Injection molding Preprocessing

Drying is highly recommended for conductive carbon based ESD grades of Hostaform®. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3 hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

Injection molding Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.